

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPB042N10N3 G	**Issued**	08. April 2022
MA#	MA005711036		
Package	PG-TO263-3-2	**Weight***	1564.98 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.870	0.57	0.57	5668	5668
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.43	19.46	194268	194521
wire	non noble metal	aluminium	7429-90-5	11.568	0.74	0.74	7392	7392
encapsulation	inorganic material	zincoxide	1314-13-2	6.757	0.43		4318	
	miscellaneous	miscellaneous	-	27.028	1.73		17271	
	plastics	epoxy resin	-	101.355	6.48		64765	
	inorganic material	silicondioxide	60676-86-0	540.561	34.54	43.18	345411	431765
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6170	6170
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.123	0.01		79	
	noble metal	silver	7440-22-4	0.154	0.01		98	
	non noble metal	lead	7439-92-1	5.877	0.38	0.40	3755	3932
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		350	
	non noble metal	copper	7440-50-8	547.666	34.97	35.02	349950	350405
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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